Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose power and switching such as output or driver stages in applications such as switching regulators, converters, and power amplifiers.

Features

- Lead Formed for Surface Mount Application in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves ("-1" Suffix)
- Electrically Similar to Popular D44H/D45H Series
- Low Collector Emitter Saturation Voltage
 - $V_{CE(sat)} = 1.0$ Volt Max @ 8.0 Amperes
- Fast Switching Speeds
- Complementary Pairs Simplifies Designs
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V
- These are Pb-Free Packages

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	80	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current – Continuous – Peak	Ι _C	8 16	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	20 0.16	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.75 0.014	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	R_{\thetaJC}	6.25	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	71.4	°C/W
Lead Temperature for Soldering	ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

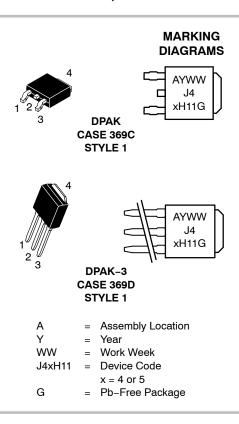
1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

http://onsemi.com

SILICON POWER TRANSISTORS 8 AMPERES 80 VOLTS, 20 WATTS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Semiconductor Components Industries, LLC, 2011 January, 2011 – Rev. 10

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS		•				
Collector–Emitter Sustaining Voltage $(I_C = 30 \text{ mA}, I_B = 0)$		V _{CEO(sus)}	80			Vdc
Collector Cutoff Current (V _{CE} = Rated V _{CEO} , V _{BE} = 0)		I _{CES}			1.0	μA
Emitter Cutoff Current (V _{EB} = 5 Vdc)		I _{EBO}			1.0	μΑ
ON CHARACTERISTICS		•	•			•
Collector–Emitter Saturation Voltage $(I_C = 8 \text{ Adc}, I_B = 0.4 \text{ Adc})$		V _{CE(sat)}			1	Vdc
Base-Emitter Saturation Voltage $(I_C = 8 \text{ Adc}, I_B = 0.8 \text{ Adc})$		V _{BE(sat)}			1.5	Vdc
DC Current Gain (V _{CE} = 1 Vdc, I _C = 2 Adc)		h _{FE}	60			-
DC Current Gain (V _{CE} = 1 Vdc, I _C = 4 Adc)			40			
DYNAMIC CHARACTERISTICS		•	•	•	•	•
Collector Capacitance (V _{CB} = 10 Vdc, f _{test} = 1 MHz)	MJD44H11 MJD45H11	C _{cb}		45 130		pF
Gain Bandwidth Product (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 20 MHz)	MJD44H11 MJD45H11	fT		85 90		MHz
SWITCHING TIMES						
Delay and Rise Times (I _C = 5 Adc, I _{B1} = 0.5 Adc)	MJD44H11 MJD45H11	t _d + t _r		300 135		ns
Storage Time (I _C = 5 Adc, I _{B1} = I _{B2} = 0.5 Adc)	MJD44H11 MJD45H11	t _s		500 500		ns
Fall Time (I _C = 5 Adc, I _{B1} = I _{B2} = 0.5 Adc	MJD44H11 MJD45H11	t _f		140 100		ns

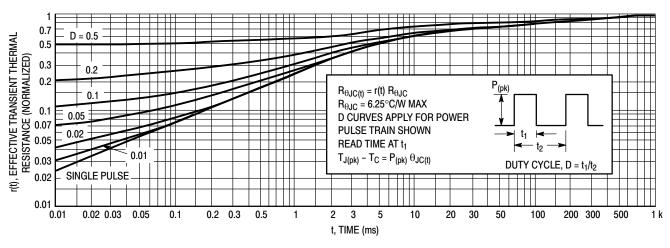
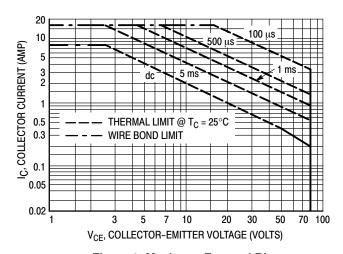
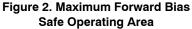


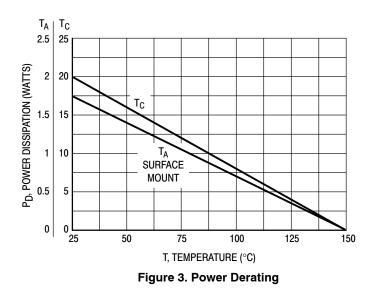
Figure 1. Thermal Response

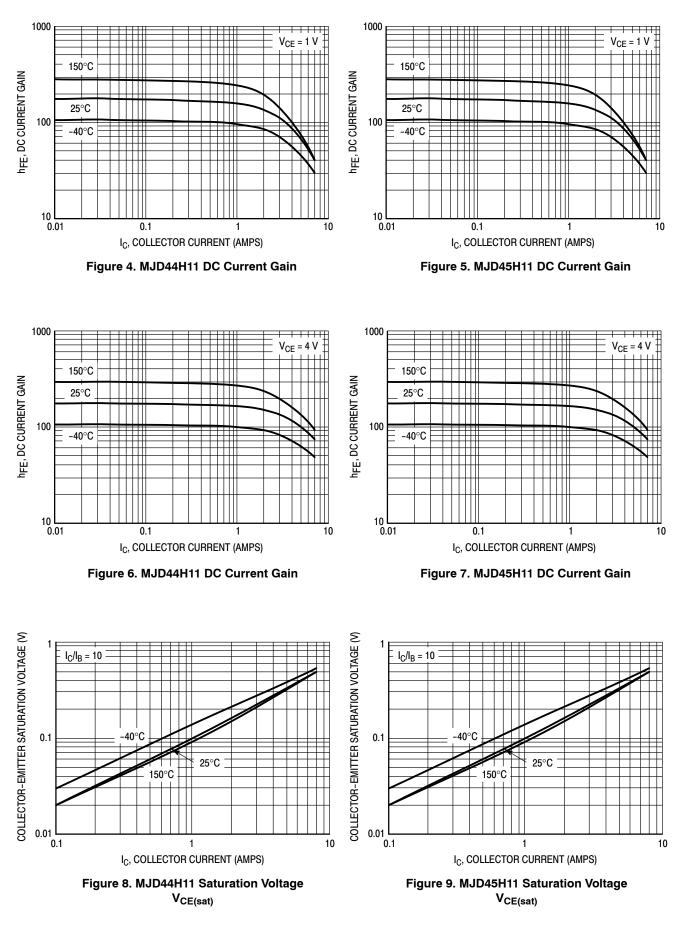


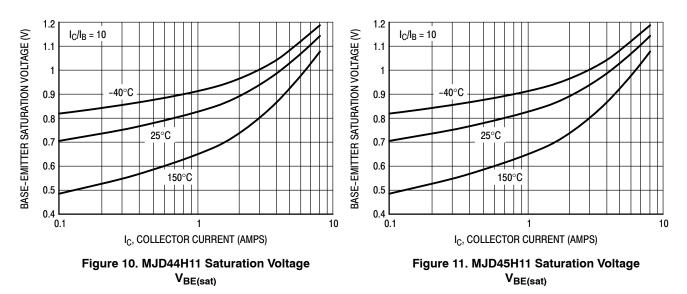


There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 2 is based on $T_{J(pk)} = 150^{\circ}$ C; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \le 150^{\circ}$ C. $T_{J(pk)}$ may be calculated from the data in Figure 1. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.







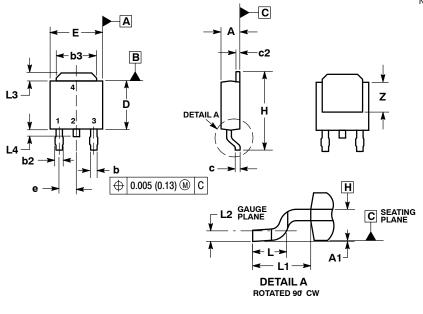
ORDERING INFORMATION

Device	Package Type	Package	Shipping [†]	
MJD44H11G	DPAK (Pb–Free)	369C	75 Inite / Deil	
MJD44H11-1G	DPAK-3 (Pb-Free)	369D	- 75 Units / Rail	
MJD44H11RLG	DPAK (Pb–Free)		1800 Tape & Reel	
MJD44H11T4G	DPAK (Pb–Free)		2500 Tape & Reel	
MJD44H11T5G	DPAK (Pb–Free)	369C		
MJD45H11G	DPAK (Pb–Free)			
MJD45H11-1G	DPAK-3 (Pb-Free)	369D	- 75 Units / Rail	
MJD45H11RLG	DPAK (Pb-Free)		1800 Tape & Reel	
MJD45H11T4	DPAK	369C		
MJD45H11T4G	DPAK (Pb-Free)]	2500 Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK CASE 369C-01 **ISSUE D**



NOTES:

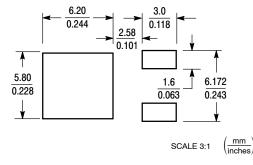
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	0.108 REF 2.74 REF		REF	
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Ζ	0.155		3.93		

SOLDERING FOOTPRINT*

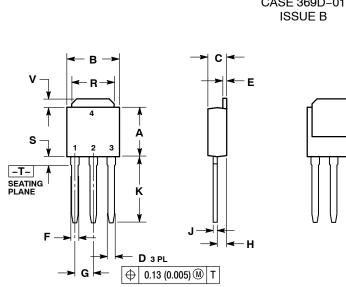
STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER

- 4. COLLECTOR

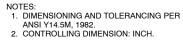


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



DPAK-3 CASE 369D-01



	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
К	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Ζ	0.155		3.93	

STYLE 1:

Ζ

BASE PIN 1. 2. COLLECTOR

3. FMITTER COLLECTOR 4.

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